



Features

- Shielded construction
- Unit height of 4 mm
- Inductance range: 0.5 to 1.8 μ H
- Current up to 13 A
- RoHS compliant*

Applications

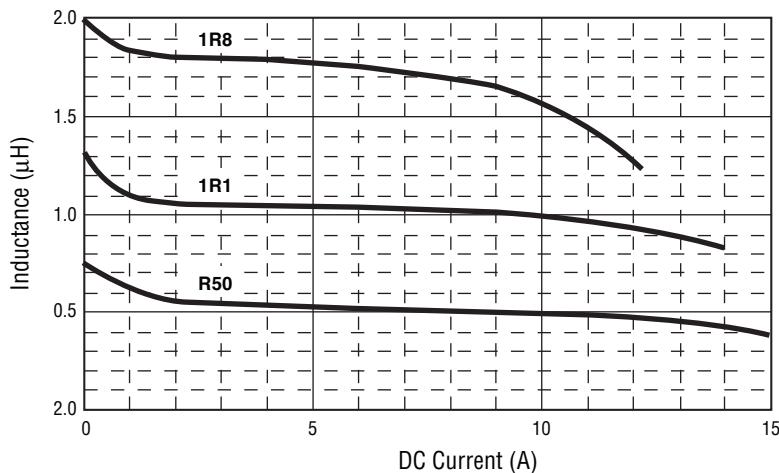
- Input/output of DC/DC converters
- Power supplies for:
 - Portable communications equipment
 - Camcorders
 - LCD TVs
 - Car audio systems

SRP1204 Series - Shielded Power Inductors

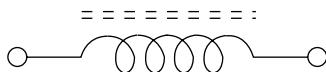
Electrical Specifications

Bourns Part No.	Initial Inductance L ₀ (μ H)	Inductance at Flat Point L ₁ (μ H)	Flat Point Ref. (A)	I _{rms} (A)	I _{sat} (A)	DCR (m Ω) Max.
SRP1204-R50M	0.75 \pm 20 %	0.55 \pm 20 %	2.0	13.0	14.0	3.0
SRP1204-1R1M	1.30 \pm 20 %	1.10 \pm 20 %	2.0	12.0	13.0	4.5
SRP1204-1R8M	2.00 \pm 20 %	1.80 \pm 20 %	2.0	10.0	11.0	6.0

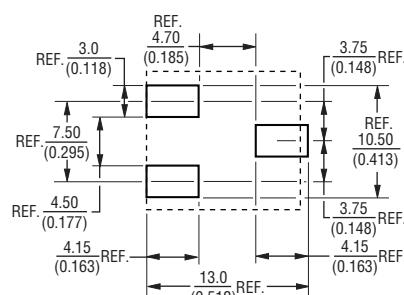
L vs I Charts



Electrical Schematic



Recommended Layout



General Specifications

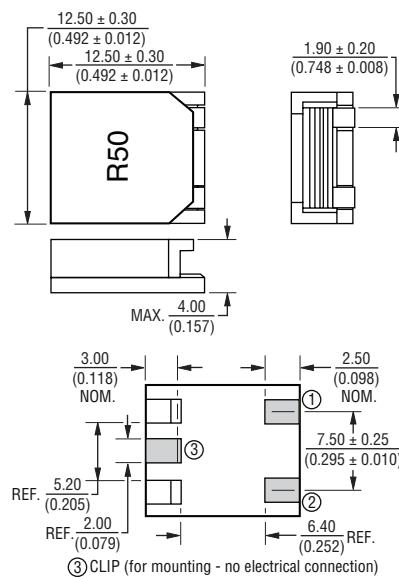
Test Voltage	1 V
Test Frequency	100 KHz
Reflow Soldering ..	230 °C; 50 sec. max.
Operating Temperature	-40 °C to +125 °C (Temperature rise included)
Storage Temperature	-40 °C to +125 °C
Resistance to Soldering Heat	+245 °C for 10 sec.
Moisture Sensitivity Level	1
ESD Classification (HBM)	N/A

¹ Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

Materials

Core	Ferrite ER
Wire	Enamelled copper
Terminal	Cu/Ni/Sn
Rated Current	Ind. drops 20 % at Isat
Temperature Rise	40 °C at rated I _{rms}
Packaging	800 pcs. per 13-inch reel

Product Dimensions



DIMENSIONS: MM
(INCHES)

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

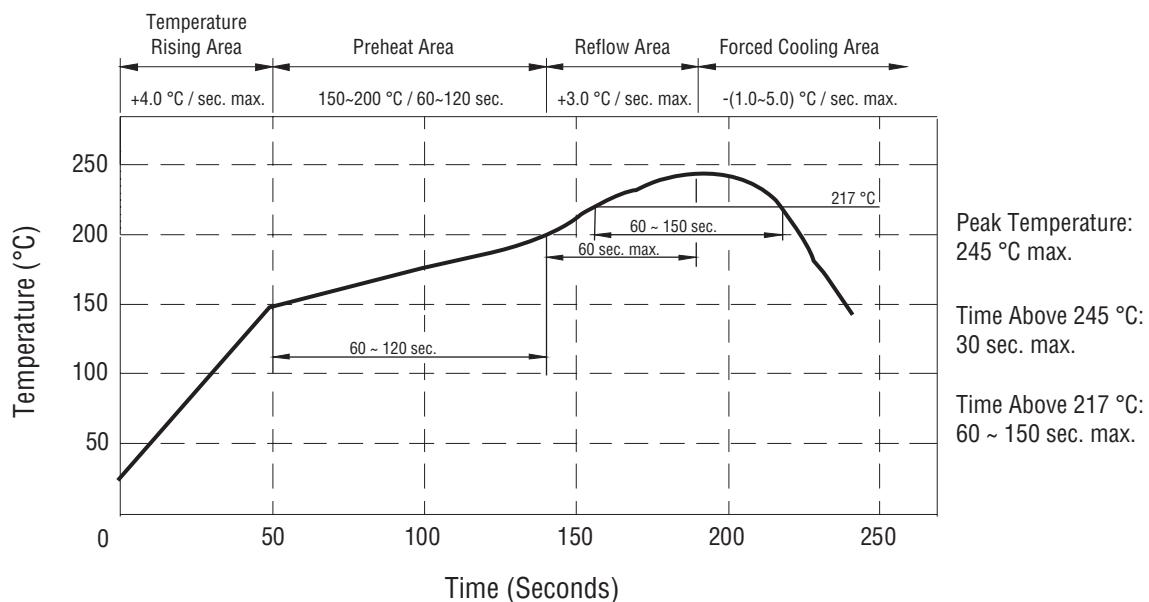
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.

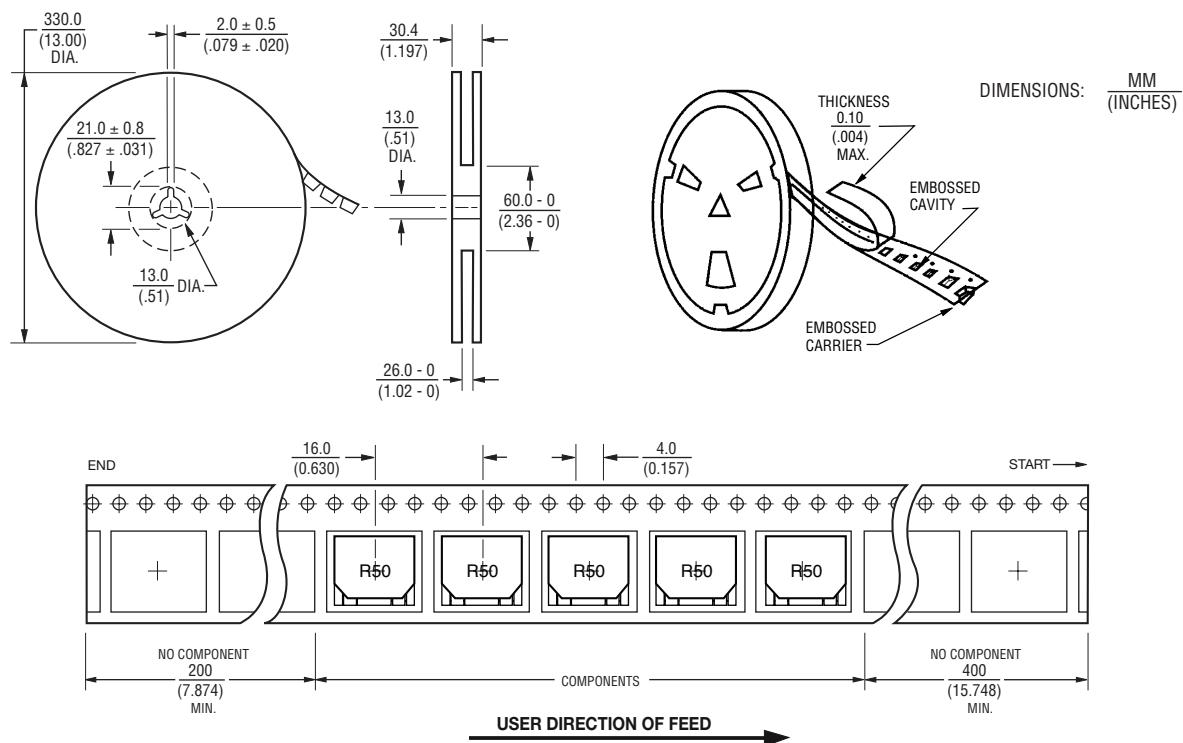
SRP1204 Series - Shielded Power Inductors

BOURNS®

Soldering Profile



Packaging Specifications



REV. 09/17

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